

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/supportform
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **02/25/2019**

Results for "TPS8268180SIPR"

Summary Results											
Search part number	TI part number	RoHS status	REACH status	Green status	IEC 62474 DB	Package	pins	Assembly site	Lead/ball finish	MSL/reflow ratings	Mass (mg)***
TPS8268180SIPR	TPS8268180SIPR*		Y		N	SIP**	9	TI PHILIPPINES CLARK A/T		Level---	0.000000

*Part Number

No material contents are available for this part.

** Pb-Free or Green Alternative BGA Parts

A Pb-Free or Green version of this BGA device may be available under a new part number. Typically, the package code for a device is embedded in the part number. Package codes Gxx, YEx (where x can be any letter), YE and WAS will be changed to new codes during the conversion to Pb-Free and Green. The new codes are Zxx, YZx, YZ and WAZ. Flip-chip BGA devices may also have a Cxx version which is 100% RoHS compliant (the Zxx version of a flip-chip BGA device is RoHS compliant with an exemption). To learn more, contact your TI sales rep.

***Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See [Product Content Methodology](#).

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact [TI customer support](#).

TI's packing materials (boxes, trays, etc) comply with EU Directive 2004/12/EC for Packaging and Packaging Waste Material.

Content details for TI's packing materials are available at www.ti.com/ecoinfo.

Signature: [\(click here for a fuller statement with a signed certificate\)](#).

Name/Title: Robert Furtaw, Vice President, Worldwide SC Quality

For further environmental statements, please go to www.ti.com/ecoinfo

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RoHS:TI defines "RoHS Compliant" to mean semiconductor products that are compliant with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials unless exempt. Where designed to be soldered at high temperatures, TI "RoHS Compliant" products are suitable for use in specified lead-free processes.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with RoHS pursuant to an exemption.

Green: TI defines "Green" to mean free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous plastic materials such as mold compound material). To satisfy customer requests, efforts through early 2Q09 are being made to verify that all non-metal homogeneous material contained in TI Green semiconductor products meet the proposed industry standard threshold levels of <=1000 ppm (0.1%) each of brominated flame retardants (BFRs) and chlorinated flame retardants (CFRs). It includes BeO to be <= 1000ppm (0.1%).